


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16068	
1.3 Title of PCN	ASE Kaohsiung (Taiwan) LQFP 14x14 package Copper Palladium bonding wire introduction on STM32G47x and STM32G48x listed products.	
1.4 Product Category	STM32G471x, STM32G473x, STM32G474x, STM32G483x and STM32G484x.	
1.5 Issue date	2026-06-16	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	ASE KaoHsiung (Taiwan)

**4. Description of change**

	<b>Old</b>	<b>New</b>
4.1 Description	Current Wire bonding material: - Amkor ATP (Philippines) gold wire - ASE KaoHsiung (Taiwan) gold wire	Current Wire bonding material: - Amkor ATP (Philippines) gold wire - ASE KaoHsiung (Taiwan) gold wire New Wire bonding material : - ASE KaoHsiung (Taiwan) copper palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

**5. Reason / motivation for change**

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

6.1 Description	Traceability ensured by ST Internal tools
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**7. Timing / schedule**

7.1 Date of qualification results	2026-04-30
7.2 Intended start of delivery	2026-07-10
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

8.1 Description	16068 MDG-GPM-RER2304-PCN16068 V5.0-ASE LQFP7x7 to 20x20 CuPd-Rel Eval Report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	<b>Issue Date</b>	2026-06-16

**9. Attachments (additional documentations)**

16068 Public product.pdf  
16068 MDG-GPM-RER2304-PCN16068 V5.0-ASE LQFP7x7 to 20x20 CuPd-Rel Eval Report.pdf  
16068 \_Additional information.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G473QET6	
	STM32G474QET3	
	STM32G474QET6	
	STM32G474QET6TR	
	STM32G483QET6	
	STM32G484QET6	
	STM32G473QBT6	

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